

SLOVENSKI STANDARD

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01-december-2016

**Modeliranje integriranih vezij (IC) za elektromagnetno združljivost (EMC) - 4. del:
Modeli integriranih vezij za vedenjsko simulacijo RF odpornosti - Modeliranje
odpornosti integriranih vezij proti prevajanim motnjam (ICIM-CI) (IEC 62433-
4:2016)**

EMC IC modelling - Part 4: Models of Integrated Circuits for RF Immunity behavioural simulation - Conducted Immunity modelling (ICIM-CI) (IEC 62433-4:2016)

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EMC IC modelling - Part 2: Models of Integrated Circuits for EMI behavioural simulation - Conducted Emissions modelling (ICEM-CE) (IEC 62433-4:2016)
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EUROPEAN STANDARD
NORME EUROPÉENNE
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EN 62433-4

October 2016

ICS 31.200

English Version

**EMC IC modelling - Part 4: Models of integrated circuits for RF
immunity behavioural simulation - Conducted immunity
modelling (ICIM-CI)
(IEC 62433-4:2016)**

Modèles de circuits intégrés pour la CEM -
Partie 4: Modèles de circuits intégrés pour la simulation du
comportement d'immunité aux radiofréquences -
Modélisation de l'immunité conduite (ICIM-CI)
(IEC 62433-4:2016)

EMV-IC-Modellierung - Teil 4: Modelle integrierter
Schaltungen für die Simulation des Verhaltens der HF-
Störfestigkeit - Modellierung der Störfestigkeit gegen
leitungsgeführte Störungen (ICIM-CI)
(IEC 62433-4:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 62433-4:2016**European foreword**

The text of document 47A/988/FDIS, future edition 1 of IEC 62433-4, prepared by SC 47A “Integrated circuits” of IEC/TC 47 “Semiconductor devices” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62433-4:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-04-21
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here:
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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62132-1	-	Circuits intégrés - Mesure de l'immunité électromagnétique - Partie 1: Conditions générales et définitions	EN 62132-1	-
IEC 62132-4	-	Circuits intégrés - Mesure de l'immunité électromagnétique 150 kHz à 1 GHz - Partie 4: Méthode d'injection directe de puissance RF	EN 62132-4	-
IEC 62433-2	-	Modèles de circuits intégrés pour la CEM - EN 62433-2 Partie 2: Modèles de circuits intégrés pour la simulation du comportement lors de perturbations électromagnétiques - https://standards.itecatalyst.sist-cm6b8-f3e1-4793-b6df-99a561fa/sist-en-62433-2-2016 Modélisation des émissions conduites (ICEM-CE)		-
ISO 8879	1986	Traitemennt de l'information - Systèmes bureautiques - Langage normalisé de balisage généralisé (SGML)	-	-
ISO/IEC 646	1991	Technologies de l'information - Jeu ISO de caractères codés à 7 éléments pour l'échange d'information		-
CISPR 17	-	Méthodes de mesure des caractéristiques d'antiparasitage des dispositifs de filtrage CEM passifs	EN 55017	-

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



EMC IC modellingⁱTeh STANDARD PREVIEW
Part 4: Models of integrated circuits for RF immunity behavioural simulation –
Conducted immunity modelling (ICIM-CI)

Modèles de circuits intégrés pour la CEM –
Partie 4: Modèles de circuits intégrés pour la simulation du comportement
d'immunité aux radiofréquences – Modélisation de l'immunité conduite (ICIM-CI)

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CONTENTS

FOREWORD.....	7
1 Scope.....	9
2 Normative references.....	9
3 Terms, definitions, abbreviations and conventions	10
3.1 Terms and definitions	10
3.2 Abbreviations	11
3.3 Conventions.....	11
4 Philosophy	12
5 ICIM-CI model description.....	12
5.1 General.....	12
5.2 PDN description	14
5.3 IBC description	15
5.4 IB description	16
6 CIML format	17
6.1 General.....	17
6.2 CIML structure	18
6.3 Global keywords	19
6.4 Header section.....	19
6.5 Lead definitions.....	20
6.6 SPICE macro-models	21
6.7 Validity section.....	23
6.7.1 General.....	23
6.7.2 Attribute definitions.....	23
6.8 PDN.....	25
6.8.1 General	25
6.8.2 Attribute definitions	26
6.8.3 PDN for a single-ended input or output	29
6.8.4 PDN for a differential input	36
6.8.5 PDN multi-port description.....	39
6.9 IBC	40
6.9.1 General	40
6.9.2 Attribute definitions	41
6.10 IB	42
6.10.1 General	42
6.10.2 Attribute definitions	43
6.10.3 Description	48
7 Extraction.....	50
7.1 General.....	50
7.2 Environmental extraction constraints	50
7.3 PDN extraction.....	51
7.3.1 General	51
7.3.2 S/Z-/Y-parameter measurement	51
7.3.3 RFIP technique	51
7.4 IB extraction.....	52
7.4.1 General	52
7.4.2 Direct RF power injection test method	52

7.4.3	RF Injection probe test method	54
7.4.4	IB data table	55
7.5	IBC	56
8	Validation of ICIM-CI hypotheses	56
8.1	General	56
8.2	Linearity	57
8.3	Immunity criteria versus transmitted power	58
9	Model usage	59
Annex A (normative) Preliminary definitions for XML representation		61
A.1	XML basics	61
A.1.1	XML declaration	61
A.1.2	Basic elements	61
A.1.3	Root element	61
A.1.4	Comments	62
A.1.5	Line terminations	62
A.1.6	Element hierarchy	62
A.1.7	Element attributes	62
A.2	Keyword requirements	62
A.2.1	General	62
A.2.2	Keyword characters	63
A.2.3	Keyword syntax	63
A.2.4	File structure	63
A.2.5	Values	65
Annex B (informative) ICIM-CI example with disturbance load		68
Annex C (informative) Conversions between parameter types		69
C.1	General	69
C.2	Single-ended input or output	69
C.3	Differential input or output	70
Annex D (informative) Example of ICIM-CI macro-model in CIML format		74
Annex E (normative) CIML Valid keywords and usage		79
E.1	Root element keywords	79
E.2	File header keywords	79
E.3	<i>Validity</i> section keywords	81
E.4	Global keywords	81
E.5	<i>Lead</i> keyword	82
E.6	<i>Lead_definitions</i> section attributes	82
E.7	<i>Macromodels</i> section attributes	83
E.8	<i>Pdn</i> section keywords	84
E.8.1	<i>Lead</i> element keywords	84
E.8.2	<i>Netlist</i> section keywords	86
E.9	<i>Ibc</i> section keywords	87
E.9.1	<i>Lead</i> element keywords	87
E.9.2	<i>Netlist</i> section keywords	89
E.10	<i>Ib</i> section keywords	89
E.10.1	<i>Lead</i> element keywords	89
E.10.2	<i>Max_power_level</i> section keywords	91
E.10.3	<i>Voltage</i> section keywords	91
E.10.4	<i>Current</i> section keywords	93

E.10.5	<i>Power section keywords</i>	94
E.10.6	<i>Test_criteria section keywords</i>	95
Annex F (informative)	PDN impedance measurement methods using vector network analyzer	97
F.1	General.....	97
F.2	Conventional one-port method.....	97
F.3	Two-port method for low impedance measurement.....	97
F.4	Two-port method for high impedance measurement	98
Annex G (informative)	RFIP measurement method description	99
G.1	General.....	99
G.2	Obtaining immunity parameters	99
Annex H (informative)	Immunity simulation with ICIM model based on pass/fail test	101
H.1	ICIM-CI macro-model of a voltage regulator IC	101
H.1.1	General	101
H.1.2	PDN extraction.....	101
H.1.3	IB extraction	101
H.1.4	SPICE-compatible macro-model	102
H.2	Application level simulation and failure prediction	102
Annex I (informative)	Immunity simulation with ICIM model based on non pass/fail test	104
Bibliography	iTeh STANDARD PREVIEW	106

Figure 1 – Example of ICIM-CI model structure.....	13
Figure 2 – Example of an ICIM-CI model of an electronic board	14
Figure 3 – Example of an IBC network.....	16
Figure 4 – ICIM-CI model representation with different blocks.....	16
Figure 5 – CIML inheritance hierarchy	18
Figure 6 – Example of a netlist file defining a sub-circuit.....	22
Figure 7 – PDN electrical schematics	29
Figure 8 – PDN represented as a one-port black-box	29
Figure 9 – PDN represented as S-parameters in Touchstone format	32
Figure 10 – PDN represented as two-port S-parameters in Touchstone format	33
Figure 11 – Example structure for defining the PDN using circuit elements.....	34
Figure 12 – Example of a single-ended PDN Netlist main circuit definition.....	35
Figure 13 – Example of a single-ended PDN Netlist with both sub-circuit and main circuit definitions.....	35
Figure 14 – Differential input schematic.....	37
Figure 15 – PDN represented as a two-port black-box	37
Figure 16 – PDN data format for differential input or output.....	37
Figure 17 – Differential inputs of an operational amplifier example	39
Figure 18 – ICIM-CI Model for a 74HC08 component	40
Figure 19 – Example IB file obtained from DPI measurement	50
Figure 20 – Test setup of the DPI immunity measurement method as specified in IEC 62132-4	52
Figure 21 – Principle of single and multi-pin DPI.....	53
Figure 22 – Electrical representation of the DPI test setup	54
Figure 23 – Test setup of the RFIP measurement method derived from the DPI method	55

Figure 24 – Example setup used for illustrating ICIM-CI hypotheses	57
Figure 25 – Example of linearity assumption validation	58
Figure 26 – Example of transmitted power criterion validation	59
Figure 27 – Use of the ICIM-CI macro-model for simulation	59
Figure A.1 – Multiple XML (CIML) files	64
Figure A.2 – XML files with data files (*.dat)	64
Figure A.3 – XML files with additional files	65
Figure B.1 – ICIM-CI description applied to an oscillator stage for extracting IB	68
Figure C.1 – Single-ended DI	69
Figure C.2 – Differential DI	70
Figure C.3 – Two-port representation of a differential DI	70
Figure C.4 – Simulation of common-mode injection on a differential DI based on DPI	72
Figure C.5 – Equivalent common-mode input impedance of a differential DI	72
Figure C.6 – Determination of transmitted power for a differential DI	72
Figure D.1 – Test setup on an example LIN transceiver	74
Figure D.2 – PDN data in touchstone format (s2p), data measured using VNA	76
Figure D.3 – PDN data of leads 6 (LIN) and 7 (VCC)	77
Figure D.4 – IB data in ASCII format (.txt), data measured using DPI method – Injection on VCC pin https://standards.iteh.ai/catalog/standards/sist/96b6b6b8-f3e1-4793-b6df-0e91a5611af/sist-en-62433-4-2016	77
Figure D.5 – IB data for injection on VCC pin https://standards.iteh.ai/catalog/standards/sist/96b6b6b8-f3e1-4793-b6df-0e91a5611af/sist-en-62433-4-2016	78
Figure F.1 – Conventional one-port S-parameter measurement	97
Figure F.2 – Two-port method for low impedance measurement https://standards.iteh.ai/catalog/standards/sist/96b6b6b8-f3e1-4793-b6df-0e91a5611af/sist-en-62433-4-2016	98
Figure F.3 – Two-port method for high impedance measurement https://standards.iteh.ai/catalog/standards/sist/96b6b6b8-f3e1-4793-b6df-0e91a5611af/sist-en-62433-4-2016	98
Figure G.1 – Test setup of the RFIP measurement method derived from DPI method	99
Figure G.2 – Principle of the RFIP measurement method	99
Figure H.1 – Electrical schematic for extracting the voltage regulator's ICIM-CI	101
Figure H.2 – ICIM-CI extraction on the voltage regulator example	102
Figure H.3 – Example of a SPICE-compatible ICIM-CI macro-model of the voltage regulator	102
Figure H.4 – Example of a board level simulation on the voltage regulator's ICIM-CI with PCB model and other components including parasitic elements	103
Figure H.5 – Incident power as a function of frequency that is required to create a defect with a 10 nF filter	103
Figure I.1 – Example of an IB file for a given failure criterion	104
Figure I.2 – Comparison of simulated transmitted power and measured immunity behaviour	105
 Table 1 – Attributes of <i>Lead</i> keyword in the <i>Lead_definitions</i> section	20
Table 2 – Compatibility between the <i>Mode</i> and <i>Type</i> fields for correct CIML annotation	20
Table 3 – <i>Subckt</i> definition	21
Table 4 – Definition of the <i>Validity</i> section	23
Table 5 – Definition of the <i>Lead</i> keyword for <i>Pdn</i> section	25
Table 6 – Valid data formats and their default units in the <i>Pdn</i> section	28
Table 7 – Valid file extensions in the <i>Pdn</i> section	28
Table 8 – Valid fields of the <i>Lead</i> keyword for single-ended PDN	30

Table 9 – <i>Netlist</i> definition.....	34
Table 10 – Valid fields of the <i>Lead</i> keyword for differential PDN.....	38
Table 11 – Differences between the <i>Pdn</i> and <i>Ibc</i> section fields	41
Table 12 – Valid fields of the <i>Lead</i> keyword for IBC definition	42
Table 13 – Definition of the <i>Lead</i> keyword in <i>lb</i> section.....	43
Table 14 – <i>Max_power_level</i> definition	44
Table 15 – <i>Voltage</i> , <i>Current</i> and <i>Power</i> definition	45
Table 16 – <i>Test_criteria</i> definition	45
Table 17 – Default values of <i>Unit_voltage</i> , <i>Unit_current</i> and <i>Unit_power</i> tags as a function of data format	48
Table 18 – Valid file extensions in the <i>lb</i> section.....	48
Table 19 – Example of IB table pass/fail criteria	56
Table A.1 – Valid logarithmic units	66
Table C.1 – Single-ended parameter conversion.....	70
Table C.2 – Differential parameter conversion	71
Table C.3 – Power calculation.....	73
Table E.1 – Root element keywords	79
Table E.2 – <i>Header</i> section keywords.....	80
Table E.3 – <i>Validity</i> section keywords.....	81
Table E.4 – Global keywords.....	82
Table E.5 – <i>Lead</i> element definition	82
Table E.6 – <i>Lead_definitions</i> section keywords.....	83
Table E.7 – <i>Macromodels</i> section keywords.....	83
Table E.8 – <i>Lead</i> element keywords in the <i>Pdn</i> section.....	84
Table E.9 – Netlist section keywords	87
Table E.10 – <i>Lead</i> element keywords in the <i>Ibc</i> section	87
Table E.11 – <i>Lead</i> element keywords in the <i>lb</i> section.....	90
Table E.12 – <i>Max_power_level</i> section keywords	91
Table E.13 – <i>Voltage</i> section keywords	92
Table E.14 – <i>Current</i> section keywords	93
Table E.15 – <i>Power</i> section keywords	94
Table E.16 – <i>Test_criteria</i> section keywords	96

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EMC IC MODELLING –**Part 4: Models of integrated circuits for RF immunity behavioural simulation – Conducted immunity modelling (ICIM-CI)****FOREWORD**

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International Standard IEC 62433-4 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

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FDIS	Report on voting
47A/988/FDIS	47A/989/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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EMC IC MODELLING –

Part 4: Models of integrated circuits for RF immunity behavioural simulation – Conducted immunity modelling (ICIM-CI)

1 Scope

This part of IEC 62433 specifies a flow for deriving a macro-model to allow the simulation of the conducted immunity levels of an integrated circuit (IC). This model is commonly called Integrated Circuit Immunity Model – Conducted Immunity, ICIM-CI. It is intended to be used for predicting the levels of immunity to conducted RF disturbances applied on IC pins.

In order to evaluate the immunity threshold of an electronic device, this macro-model will be inserted in an electrical circuit simulation tool.

This macro-model can be used to model both analogue and digital ICs (input/output, digital core and supply). This macro-model does not take into account the non-linear effects of the IC.

The added value of ICIM-CI is that it could also be used for immunity prediction at board and system level through simulations.

THE STANDARD PREVIEW

This part of IEC 62433 has two main parts:

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- the electrical description of ICIM-CI macro-model elements;
- a universal data exchange format called CIML based on XML. This format allows ICIM-CI to be encoded in a more useable and generic form for immunity simulation.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62132-1, *Integrated circuits – Measurement of electromagnetic immunity – Part 1: General conditions and definitions*

IEC 62132-4, *Integrated circuits – Measurement of electromagnetic immunity 150 kHz to 1 GHz – Part 4: Direct RF power injection method*

IEC 62433-2, *EMC IC modelling – Part 2: Models of integrated circuits for EMI behavioural simulation – Conducted emissions modelling (ICEM-CE)*

ISO 8879: 1986, *Information processing – Text and office systems – Standard Generalized Markup Language (SGML)*

ISO/IEC 646: 1991, *Information technology – ISO 7-bit coded character set for information interchange (7-Bit ASCII)*

CISPR 17, *Methods of measurement of the suppression characteristics of passive EMC filtering devices*